



# PRODUCT/PROCESS CHANGE NOTIFICATION

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PCN MPA-LOG/06/1797/2132  
Notification Date 11/09/2006

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**ST1G3234BJR, ST4G3234BJR & ST4G3235BJR Additional Back-End(AMKOR) Location.**

**LOG - ADV ANALOG/LOGIC**

**Table 1. Change Identification**

Product Identification (Product Family/Commercial Product)	ST1G3234BJR, ST4G3234BJR & ST4G3235BJR
Type of change	Package assembly location change
Reason for change	Back-End additional Sub-Con(Amkor) Location for Sawing and Tape/Reeling.
Description of the change	Currently, Backend Sub-Con(Amkor) is adding capacity, creating new line of Sawing & Tape/Reeling Facilities in Taiwan. Changes are minimal. The new line in Taiwan will use the same existing process. Current AMKOR Process: UBM + Bumping(Korea)> LaserMarking(Korea/Taiwan)> Testing (Korea/Philippines)> Sawing + Tape/Reel(Philippines). Additional AMKOR Process:- UBM + Bumping + Testing (Korea)> Laser Marking + Sawing + Tape/Reeling (Taiwan).
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	New Marking on Device, see attached file
Manufacturing Location(s)	

**Table 2. Change Implementation Schedule**

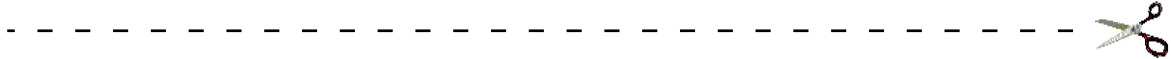
Forecasted implementation date for change	19-Jan-2007
Forecasted availability date of samples for customer	20-Oct-2006
Forecasted date for <b>STMicroelectronics</b> change Qualification Plan results availability	20-Oct-2006
Estimated date of changed product first shipment	26-Jan-2007

**Table 3. Change Responsibility**

	<b>Name</b>	<b>Signature</b>	<b>Date</b>
Division Product Manager	Francesco Italia		Oct.20 ,06
Division Q.A. Manager	Gianluigi Vitali		Oct.20 ,06
Division Marketing Manager	Steven Fong		Oct.20 ,06

**Table 4. List of Attachments**

Customer Part numbers list	
Qualification Plan results	



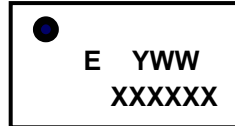
Customer Acknowledgement of Receipt		<b>PCN MPA-LOG/06/1797/2132</b>
Please sign and return to STMicroelectronics Sales Office		<b>Notification Date 11/09/2006</b>
<input type="checkbox"/> Qualification Plan Denied <input type="checkbox"/> Qualification Plan Approved  <input type="checkbox"/> Change Denied <input type="checkbox"/> Change Approved	Name:	
	Title:	
	Company:	
	Date:	
	Signature:	
Remark ..... ..... ..... ..... .....		

## Appendix 1:- Proposed Marking Changes

### Current Marking on Products



*ST1G3234BJR*



*ST4G3234BJR/ST4G3235BJR*

Where current XXXXXX is Device Code,

ST1G3234BJR:- 1G3234

ST4G3234BJR:- 4G3234

ST4G3235BJR:- 4G3235

### New Proposed Marking on Products



*ST1G3234BJR*



*ST4G3234BJR/ST4G3235BJR*

Where X is Device Code:

1:-ST1G3234BJR

2:-ST4G3234BJR

3:-ST4G3235BJR

P:- Plant BEG Code.

Y:- Year

WW:- Work Week



Reliability Evaluation Plan and Final Results  
ST1G3234BJR@P3 Sawing on Amkor Taiwan  
HCMOS6 TECHNOLOGY

LINE VCC1

PACKAGE FLIP-CHIP5 Pb Free

Test	Conditions	S.S.	Requirement	Results
HTB	TA=125°C Vbias =4.6V	77x1 Lot	Parameter deviation within spec. limits at 1000h	No parameter deviation out of spec. limits at 1000 hours
H.T.S	TA=150°C	77x1 Lot	Parameter deviation within spec. limits at 1000h	No parameter deviation out of spec. limits at 1000 hours
T.H.B.	TA=85°C – RH=85% Vbias=3.6V	77x1 Lot	Parameter deviation within spec. limits at 1000h	No parameter deviation out of spec. limits at 1000 hours
THERMAL CYCLES AIR TO AIR	TA=-40°C TO 125°C 1 HOUR/CYCLE	77x1 Lot	Parameter deviation within spec. limits at 500cycles	No parameter deviation out of spec. limits at 500 cycles
SMD MOISTURE INDUCED STRESS	IR @ Ta max= 260°C	All x1 Lot	Parameter deviation within spec. limits at end of test	No parameter deviation out of spec. limits at end of test

All DUTs are assembled on PCB

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